



## Material Content Data Sheet



<b>Sales Product Name</b>				IPZ40N04S5-3R1		<b>Issued</b>		9. June 2015	
<b>MA#</b>				MA001171640					
<b>Package</b>				PG-TSDSON-8-33		<b>Weight*</b>		36.43 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.429	1.18	1.18	11768	11768	
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		85		
	non noble metal	zinc	7440-66-6	0.012	0.03		341		
	non noble metal	iron	7439-89-6	0.249	0.68		6829		
wire	non noble metal	copper	7440-50-8	10.102	27.73	28.45	277298	284553	
	noble metal	gold	7440-57-5	0.029	0.08	0.08	805	805	
encapsulation	organic material	carbon black	1333-86-4	0.036	0.10		1001		
	plastics	epoxy resin	-	1.878	5.16		51561		
	inorganic material	silicondioxide	60676-86-0	16.322	44.79	50.05	448029	500591	
leadfinish	non noble metal	tin	7440-31-5	0.400	1.10	1.10	10987	10987	
plating	noble metal	silver	7440-22-4	0.086	0.24	0.24	2350	2350	
solder	noble metal	silver	7440-22-4	0.019	0.05		511		
	non noble metal	tin	7440-31-5	0.015	0.04		408		
	non noble metal	lead	7439-92-1	0.711	1.95	2.04	19505	20424	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		16		
	non noble metal	zinc	7440-66-6	0.002	0.01		64		
	non noble metal	iron	7439-89-6	0.047	0.13		1290		
	non noble metal	copper	7440-50-8	1.908	5.24	5.38	52363	53733	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		34		
	non noble metal	zinc	7440-66-6	0.005	0.01		138		
	non noble metal	iron	7439-89-6	0.100	0.28		2755		
	non noble metal	copper	7440-50-8	4.075	11.19	11.48	111862	114789	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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